

2-Channel RGB Charge Pump LED Driver with Illumination





BD2812GU

General Description

The BD2812GU is a RGB LED driver for decorative purposes. This RGB driver has lighting patterns and can illuminate LEDs without load of CPU. This RGB driver is best-suited for illumination using RGB LEDs, and decoration using monochrome LEDs. The DC/DC block adopts a charge pump system and not uses an inductor. This RGB driver has been miniaturized through the use of a VCSP85H3 (3.1 mm×3.1 mm 0.5 mm pitch) chip size package.

Features

- ■RGB LED driver (dual drivers)
 - A slope control function is incorporated (allowing dual drivers to be controlled independently).
 - Slope control can be implemented using the DC current.
 - Two modes "continuous illumination mode" and "illumination single cycle mode" are supported.
 - Independent external ON/OFF synchronizing terminals (of dual drivers) are provided.
 - Multiple drivers can be used concurrently by using the I²C address change function and supporting reference clock I/O.
 - Low consumption operation is possible by the Sleep operation mode function.

Features – continued

- ■Charge pump system DC/DC
 - Boost magnification is changed automatically (x1, x1.5, x2)
 - Supports an output voltage auto mode function (It adjusts to voltage required for LED automatically)
 - Supports an output voltage fixed mode function (3.9V/4.2V/4.5V/4.8V)
 - Mounts a soft start function, an over voltage protection function (auto recovery type) and an over current protection (auto recovery)
- ■Thermal shutdown
- ■I²C BUS fast mode support (maximum rate: 400 kHz) format
 - A device address can be changed via an external pin.

Key Specifications

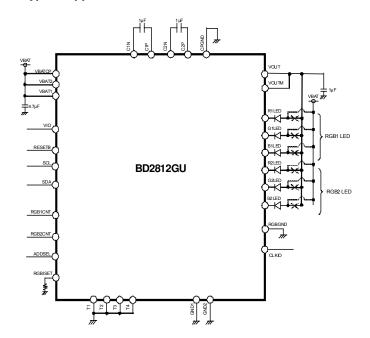
Operating power supply voltage range: 2.7V to 5.5V
 LED maximum setting current: 30.48mA (Max.)
 Oscillator Frequency: 1.0MHz(Typ.)
 Operating temperature range: -40°C to +85°C

● Package W(Typ.) x D(Typ.) x H(Max.) VCSP85H3 3.10mm x 3.10mm x 1.00mm

Application

■ Mobile Phone, Portable device

Typical Application Circuit



●Pin Configuration [Bottom View]

F	T4	VBAT1	B2LED	RGBGND	B1LED	Т3
E	GND1	RGBISET	G2LED	R2LED	G1LED	R1LED
D	RGB2CNT	RGB1CNT			VOUTM	VOUT
С	VBAT2	CLKIO	index		C1P	C2P
В	GND2	SCL	SDA	ADDSEL	C1N	VBATCP
Α	T1	VIO	RESETB	CPGND	C2N	T2
	1	2	3	4	5	6

OProduct structure: Silicon monolithic integrated circuit OThis product is not designed protection against radioactive rays

● Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Maximum Applied Voltage	VMAX	7	V
Power Dissipation	Pd	1460 ^{*1}	mW
Operating Temperature Range	Topr	-40 to +85	°C
Storage Temperature Range	Tstg	-55 to +150	°C

^{*1} Power dissipation deleting is -11.68mW/ °C, when it's used in over 25 °C. (It's deleting is on the board that is ROHM's standard)

●Recommended Operating Ratings (VBAT≥VIO, Ta=-40 to 85°C)

Parameter	Symbol	Ratings	Unit
VBAT Input Voltage	VBAT	2.7 to 5.5	V
VIO Pin Voltage	VIO	1.65 to 3.3	V

● Electrical Characteristics (Unless otherwise specified, Ta=25°C, VBAT=3.6V, VIO=1.8V)

Parameter	Symbol	Limits			Unit	Condition	
Farameter	Symbol	Min.	Тур.	Max.	Unit	Condition	
【Circuit Current】							
VBAT Circuit Current 1	IBAT1	-	0.1	3.0	μA	RESETB=0V, VIO =0V	
VBAT Circuit Current 2	IBAT2	-	0.5	3.0	μΑ	RESETB=0V, VIO=1.8V	
VBAT Circuit Current 3	IBAT3	-	0.8	1.2	mA	LED 6Ch ON, ILED=10mA setting Exclusive of LED current, RGBISET =120kΩ	
VBAT Circuit Current 4	IBAT4	-	61	65	mA	DC/DC x1mode, lo=60mA, VBAT=4.0V	
VBAT Circuit Current 5	IBAT5	-	92	102	mA	DC/DC x1.5mode, lo=60mA, VBAT=3.6V	
VBAT Circuit Current 6	IBAT6	-	123	140	mA	DC/DC x2mode, lo=60mA, VBAT=2.7V	
VBAT Circuit Current 7	IBAT7	-	5	7.5	μA	External clock Sleep operation mode External clock = 31.25kHz, ILED=0mA	
【LED Driver】							
LED Current Step	ILEDSTP		128		step	RGB1 group, RGB2 group	
LED Maximum Setup Current	IMAX	-	-	30.48	mA	RGB1 group, RGB2 group RGBISET=100kΩ	
LED Current Accurate	ILED	18	20	22	mA	RGB1 group, RGB2 group, Terminal voltage =1V ILED=20mA setting, RGBISET =120kΩ	
LED Current Matching	ILEDMT	-	5	10	%	RGB1 group, between RGB2 group, Terminal voltage =1V ILED=20mA setting	
LED OFF Leak Current	ILKL	-	-	1.0	μA		
【DC/DC (Charge Pump)】							
Output Voltage 1	VoCP1	-	Vf+0.2	Vf +0.25	V	At output voltage auto mode, Vf is forward direction of LED	
		3.705	3.9	4.095	V		
Output Voltage 2	VoCP2	3.99	4.2	4.41	V	At fixed voltage output mode, lo=60mA	
Output Voltage 2	VOCI 2	4.275	4.5	4.725	V	VBAT≥3.2V	
		4.56	4.8	5.04	V		
Load Stability	lout	-	-	255	mA	VBAT≥3.2V, VOUT=4V	
Oscillator Frequency	fosc	0.8	1.0	1.2	MHz		
Over Voltage Protection Detect Voltage	OVP	-	6.0	6.5	V		
Over Current Protection Detect Current	OCP	-	250	375	mA	VOUT=0V	

● Electrical Characteristics - continued (Unless otherwise specified, Ta=25 °C. VBAT=3.6V. VIO=1.8V)

Parameter	Symbol		Limits		Unit	Condition
Farameter	Symbol	Min.	Тур.	Max.	Offic	Condition
【SDA, SCL】(I ² C interface)						
L level Input Voltage	VILI	-0.3	-	0.25 ×VIO	٧	
H level Input Voltage	VIHI	0.75 ×VIO	-	VBAT +0.3	٧	
Hysteresis of Schmitt Trigger Input	Vhysl	0.05 ×VIO	-	-	V	
L Level Output Voltage	VOLI	0	-	0.3	V	SDA pin, IOL=3 mA
Input Current	linl	-10	-	10	μA	Input voltage = 0.1×VIO to 0.9×VIO
【RESETB, ADDSEL】(CMOS	S input pin)					
L Level input Voltage	VILR	-0.3	-	0.25 ×VIO	V	
H Level input Voltage	VIHR	0.75 ×VIO	-	VBAT +0.3	V	
Input Current	linR	-10	-	10	μA	Input voltage = 0.1×VIO to 0.9×VIO
【RGB1CNT, RGB2CNT】(CM	10S input pin v	vith Pull-	down res	istance)		
L Level Input Voltage	VILCNT	-0.3	-	0.25 ×VIO	V	
H Level Input Voltage	VIHCNT	0.75 ×VIO	-	VBAT +0.3	V	
Input Current	IinCNT	-	3.6	10	μΑ	Input voltage = 1.8V
【CLKIO(Output)】(CMOS out	put pin)					
L Level Output Voltage	VOLCLK	ı	-	0.2	V	IOL=1mA
H Level Output Voltage	VOHCLK	VIO -0.2	-	-	V	IOH=1mA
Output Frequency1	fclk1	200	250	300	kHz	FSEL=0 setting
Output Frequency2	fclk2	25	31.25	37.5	kHz	FSEL=1 setting
【CLKIO (Input)】(CMOS inpu	t pin with Pull-	down res	istance)			
L Level Input Voltage	VILCLK	-0.3	-	0.25 ×VIO	V	
H Level Input Voltage	VIHCLK	0.75 ×VIO	-	VIO +0.3	V	
Input Current	linCLK	-	3.6	10	μΑ	Input voltage = 1.8V

●Timing diagram

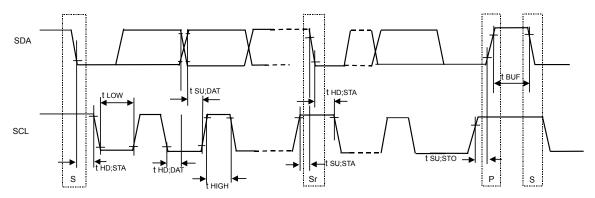


Figure 1 Timing diagram

(Unless otherwise specified, Ta=25°C, VBAT=3.6V, VIO=1.8V)

Parameter	Symbol Standard-m			ode	F	ast-mod	е	Unit
Parameter	Symbol	Min.	Тур.	Max.	Min.	Тур.	Max.	Unit
[I ² C BUS format]								
SCL clock frequency	fscl	0	-	100	0	-	400	kHz
LOW period of the SCL clock	tLOW	4.7	-	-	1.3	-	-	μs
HIGH period of the SCL clock	tHIGH	4.0	-	-	0.6	-	-	μs
Hold time (repeated) START condition After this period, the first clock is generated	thd;sta	4.0	-	-	0.6	-	-	μs
Set-up time for a repeated START condition	tsu;sta	4.7	-	-	0.6	-	-	μs
Data hold time	thd;dat	0	-	3.45	0	-	0.9	μs
Data set-up time	tsu;dat	250	-	-	100	-	-	ns
Set-up time for STOP condition	tsu;sто	4.0	_	-	0.6	-	-	μs
Bus free time between a STOP and START condition	tBUF	4.7	_	-	1.3	-	-	μs

●Pin Descriptions

n Descr	ptions						1
No	Pin No.	Pin Name	I/O	Input For Power	Level For GND	ESD Diode	Functions
1	В6	VBATCP	1	-	GND	Battery is connected	Α
2	F2	VBAT1	-	-	GND	Battery is connected	Α
3	C1	VBAT2	ı	-	GND	Battery is connected	А
4	A1	T1	ı	VBAT	GND	Test Pin (short to GND)	L
5	A6	T2	-	VBAT	GND	Test Pin (short to GND)	L
6	F6	Т3	-	VBAT	GND	Test Pin (short to GND)	L
7	F1	T4	ı	VBAT	-	Test Pin (short to GND)	В
8	A2	VIO	ı	VBAT	GND	I/O voltage source is connected	С
9	А3	RESETB		VBAT	GND	Reset input (L: RESET, H: RESET cancel)	Н
10	В3	SDA	I/O	VBAT	GND	I ² C data input	ı
11	B2	SCL		VBAT	GND	I ² C clock input	Н
12	A4	CPGND	-	VBAT	-	Ground	В
13	E1	GND1	ı	VBAT	-	Ground	В
14	B1	GND2	-	VBAT	-	Ground	В
15	F4	RGBGND	ı	VBAT	-	Ground	В
16	B5	C1N	I/O	VBAT	GND	Charge pump Capacitor is connected	F
17	C5	C1P	I/O	-	GND	Charge pump Capacitor is connected	Α
18	A5	C2N	I/O	VBAT	GND	Charge pump Capacitor is connected	F
19	C6	C2P	I/O	-	GND	Charge pump Capacitor is connected	Α
20	D6	VOUT	0	-	GND	Charge pump Output terminal	Α
21	D5	VOUTM	0	-	GND	Charge pump Output terminal	Α
22	E2	RGBISET		VBAT	GND	RGB LED reference current	G
23	E6	R1LED	I	-	GND	Red LED1 connected	Е
24	E5	G1LED	I	-	GND	Green LED1 connected	Е
25	F5	B1LED	I	-	GND	Blue LED1 connected	Е
26	E4	R2LED	I	-	GND	Red LED2 connected	Е
27	E3	G2LED	I	-	GND	Green LED2 connected	Е
28	F3	B2LED	I	-	GND	Blue LED2 connected	Е
29	D2	RGB1CNT	I	VBAT	GND	RGB1 LED external ON/OFF Synchronism (L:OFF, H:ON)*	J
30	D1	RGB2CNT	I	VBAT	GND	RGB2 LED external ON/OFF Synchronism (L:OFF, H:ON)*	J
31	B4	ADDSEL	I	VBAT	GND	I ² C device address change terminal	Н
32	C2	CLKIO	I/O	VBAT	GND	Standard clock input-and-output terminal	N
	1					ı	1

^{*} A setup of a register is separately necessary to validate it.

●Pin ESD Type

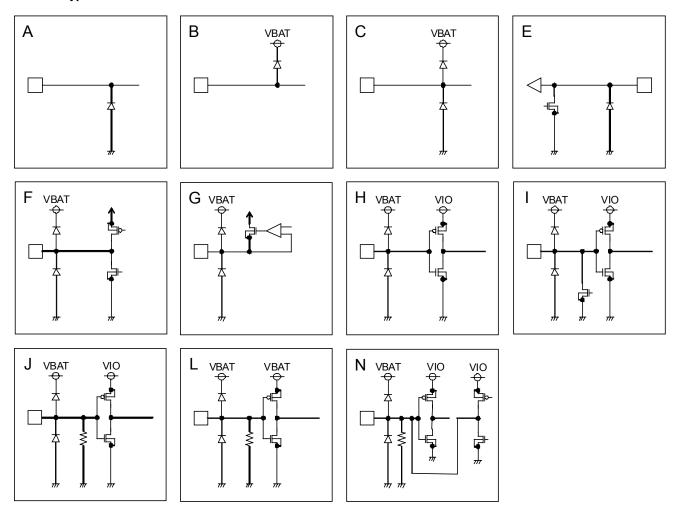
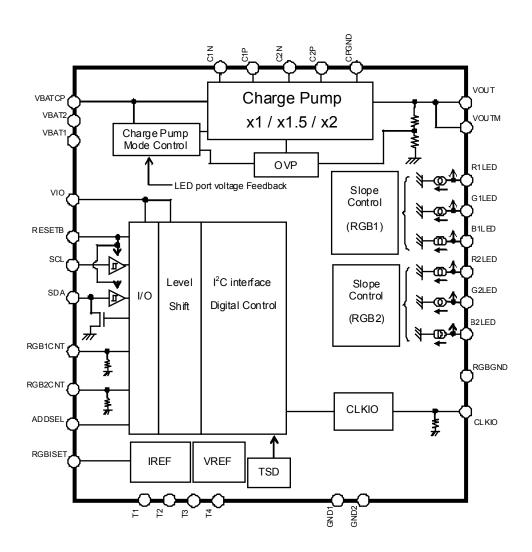


Figure 2. Pin ESD Type

● Block Diagram



●I²C BUS Format

The writing operation is based on the I²C slave standard.

• Slave address (Slave address can be changed with the external terminal ADDSEL.)

	A7	A6	A5	A4	A3	A2	A1	R/W
ADDSEL=L	0	0	1	1	0	1	0	1/0
ADDSEL=H	0	0	1	1	0	1	1	1/0

· Bit Transfer

SCL transfers 1-bit data during H. SCL cannot change signal of SDA during H at the time of bit transfer. If SDA changes while SCL is H, START conditions or STOP conditions will occur and it will be interpreted as a control signal.

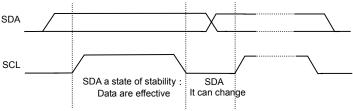


Figure 3. Bit Transfer

START and STOP condition

When SDA and SCL are H, data is not transferred on the I²C- bus. This condition indicates, if SDA changes from H to L while SCL has been H, it will become START (S) conditions, and an access start, if SDA changes from L to H while SCL has been H, it will become STOP (P) conditions and an access end.

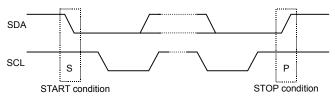


Figure 4. START and STOP condition

Acknowledge

It transfers data 8 bits each after the occurrence of START condition. A transmitter opens SDA after transfer 8bits data, and a receiver returns the acknowledge signal by setting SDA to L.

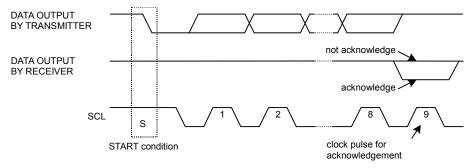


Figure 5. Acknowledge

●I²C BUS Format - continued

· Writing protocol

A register address is transferred by the next 1 byte that transferred the slave address and the write-in command. The 2nd byte is register address. The 3rd byte writes data in the internal register written in by the 2nd byte, and after 4th byte or, the increment of register address is carried out automatically. However, when a register address turns into the last address (15h), it is set to 00h by the next transmission. After the transmission end, the increment of the address is carried out

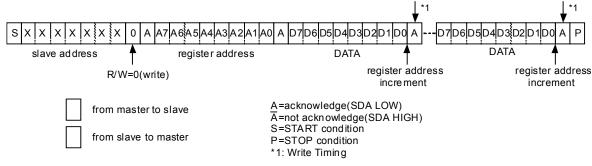
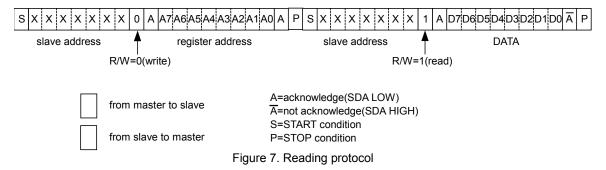


Figure 6. Writing protocol

· Reading protocol

After inputting start conditions, the register address is transferred by the next 1 byte that transferred the slave address and the write-in command. The register address to read is transmitted and the 2nd byte of stop conditions is inputted once. Start conditions are inputted again and a slave address and 1 byte of read-out command are transmitted. The internal data of the register address specified previously is outputted to the 2nd byte. After the transmission of the 2nd byte end, the master side should input the not acknowledge and input stop conditions.



● Register Map

egistei i	Write		Resister data								
Address	Or Read	D7	D6	D5	D4	D3	D2	D1	D0	Function	
00h	R/W	SLPMD	FSEL	CLKMD	CLKEN	ı	-	ı	SFTRST	Soft Reset DC/DC driver function	
01h	R/W	-	RGB2MEL	RGB2OS	RGB2EN	-	RGB1MEL	RGB1OS	RGB1EN	RGB LED control	
02h	W	SFRGB1(1)	SFRGB1(0)	SRRGB1(1)	SRRGB1(0)	-	TRGB1(2)	TRGB1(1)	TRGB1(0)	RGB1 time setup	
03h	W	-	IR11(6)	IR11(5)	IR11(4)	IR11(3)	IR11(2)	IR11(1)	IR11(0)	R1 current 1 setup	
04h	W	-	IR12(6)	IR12(5)	IR12(4)	IR12(3)	IR12(2)	IR12(1)	IR12(0)	R1 current 2 setup	
05h	W	-	-	-	-	PR1(3)	PR1(2)	PR1(1)	PR1(0)	R1 Wave pattern setup	
06h	W	-	IG11(6)	IG11(5)	IG11(4)	IG11(3)	IG11(2)	IG11(1)	IG11(0)	G1 current 1 setup	
07h	W	-	IG12(6)	IG12(5)	IG12(4)	IG12(3)	IG12(2)	IG12(1)	IG12(0)	G1 current 2 setup	
08h	W	-	-	-	-	PG1(3)	PG1(2)	PG1(1)	PG1(0)	G1 Wave pattern setup	
09h	W	-	IB11(6)	IB11(5)	IB11(4)	IB11(3)	IB11(2)	IB11(1)	IB11(0)	B1 current 1 setup	
0Ah	W	-	IB12(6)	IB12(5)	IB12(4)	IB12(3)	IB12(2)	IB12(1)	IB12(0)	B1 current 2 setup	
0Bh	W	-	-	-	-	PB1(3)	PB1(2)	PB1(1)	PB1(0)	B1 Wave pattern setup	
0Ch	W	SFRGB2(1)	SFRGB2(0)	SRRGB2(1)	SRRGB2(0)	-	TRGB2(2)	TRGB2(1)	TRGB2(0)	RGB2 time setup	
0Dh	W	-	IR21(6)	IR21(5)	IR21(4)	IR21(3)	IR21(2)	IR21(1)	IR21(0)	R2 current 1 setup	
0Eh	W	-	IR22(6)	IR22(5)	IR22(4)	IR22(3)	IR22(2)	IR22(1)	IR22(0)	R2 current 2 setup	
0Fh	W	-	-	-	-	PR2(3)	PR2(2)	PR2(1)	PR2(0)	R2 Wave pattern	
10h	W	-	IG21(6)	IG21(5)	IG21(4)	IG21(3)	IG21(2)	IG21(1)	IG21(0)	G2 current 1 setup	
11h	W	-	IG22(6)	IG22(5)	IG22(4)	IG22(3)	IG22(2)	IG22(1)	IG22(0)	G2 current 2 setup	
12h	W	-	-	-	-	PG2(3)	PG2(2)	PG2(1)	PG2(0)	G2 Wave pattern setup	
13h	W	-	IB21(6)	IB21(5)	IB21(4)	IB21(3)	IB21(2)	IB21(1)	IB21(0)	B2 current 1 setup	
14h	W	-	IB22(6)	IB22(5)	IB22(4)	IB22(3)	IB22(2)	IB22(1)	IB22(0)	B2 current 2 setup	
15h	W	-	-	-	-	PB2(3)	PB2(2)	PB2(1)	PB2(0)	B2 Wave pattern setup	
16h											
S	-		Reserved								
3Fh											
40h	R/W	VOUT(1)	VOUT(0)	DCDCMD	DCDCFON	-	-	-	-	DC/DC driver function	
41h	R/W	-	-	-	-	RGB2PW(1)	RGB2PW(0)	RGB1PW(1)	RGB1PW(0)	LED pin function	

Input "0" for "-".

Vacancy address may be use for test.

Prohibit to accessing the address that isn't mentioned and the register for test.

Address 00h <Soft Reset>

, taai oc	darese con controcct									
DIT	BIT Name	Init	Function							
DII	on manne		0	1						
D7	SLPMD	0	Illuminations Normal mode	Illuminations Sleep mode						
D6	FSEL	0	Standard clock output : 250kHz	Standard clock output : 31.25kHz						
D5	CLKMD	0	Clock Input mode	Clock Output mode						
D4	CLKEN	0	Clock input and output invalid	Clock input and output Effective						
D3	-	-	-	-						
D2	-	-	-	-						
D1	-	-	-	-						
D0	SFTRST	0	Reset Release	Reset						

Access to D7-D4 bit under operation is prohibition.

Address 01h <RGB LED control >

DIT	BIT Name	Init	Function				
ы	DII Name		0	1			
D7	-	-	-	-			
D6	RGB2MEL	0	RGB2 external control invalid	RGB2 external control valid			
D5	RGB2OS	0	RGB2 Stop	RGB2 1 periodic operation			
D4	RGB2EN	0	RGB2 Stop	RGB2 continuous operation			
D3	-	-	-	-			
D2	RGB1MEL	0	RGB1 external control invalid	RGB1 external control valid			
D1	RGB10S	0	RGB1 Stop	RGB1 1 periodic operation			
D0	RGB1EN	0	RGB1 Stop	RGB1 continuous operation			

RGB*OS returns to 0 automatically after 1 cycle operation.

RGB*EN precedes to RGB*OS. In use in 1 cycle operation, there is the necessity for RGB*EN=0.

Address 02h <RGB1 time>

NI	1	<u> </u>	Fun	ction					
Name	Init	0			1				
		SFRGB1(1)	SFRO	GB1(0)	Slope Down transition				
SFRGB1(1)	0	0		0	0				
		0		1	Wave form cycle / 16				
		1		0	Wave form cycle / 8				
SFRGB1(0)	•	1		1	Wave form cycle / 4				
SFRGB1(0)	O				alog section is not included.				
		SRRGB1(1)	SRRO	GB1(0)	Slope Up transition				
D5 SRRGB1(1)	0	0		0	0				
		0		1	Wave form cycle / 16				
		1		0	Wave form cycle / 8				
000004(0)	0	1		1	Wave form cycle / 4				
SRRGB1(0)	U		It is a theoretical value on logic control, and the reaction time of the analog section is not included. "Slope time" is the time from a slope start to a slope end.						
-	ı	-			-				
		TRGB1(2)	TRGB1(1)	TRGB1(0)) Wave form cycle				
TRGB1(2)	0	0	0	0	0.131 s				
		0	0	1	0.52 s				
		0	1	0	1.05 s				
TRGB1(1)	0	0	1	1	2.10 s				
		1	0	0	4.19 s				
		1	0	1	8.39 s				
TRGB1(0)	0	1	1	0	12.6 s				
		1	1	1	16.8 s				
	SFRGB1(0) SRRGB1(1) SRRGB1(0) - TRGB1(2)	SFRGB1(1) 0 SFRGB1(0) 0 SRRGB1(1) 0 SRRGB1(0) 0 TRGB1(2) 0 TRGB1(1) 0	SFRGB1(1) 0	SFRGB1(1) 0 SFRGB1(1) SFRGB1(2) SFRGB1(1) SFRGB1(1) SFRGB1(1) SFRGB1(1) SFRGB1(2) SFRGB1(2)	SFRGB1(1) 0 SFRGB1(1) SFRGB1(0) 0 0 0 0 0 0 0 0 0				

Setting time is counted based on the frequency of OSC. The above-mentioned value is a value at the time of Typ (1MHz).

When operating by the external clock, input frequency is a value at the time of Typ (31.25kHz). Refer to "

RGB Waveform Setting " for the detailed function of each register of this page.

Address 03h <R1 current 1setup >

DIT	BIT Name	Init				Fund	ction						
DII	Name	Ш		0			1						
D7	-	-		-					-				
D6	IR11(6)	0	IR11(6)	11(6) IR11(5) IR11(4) IR11(3) IR11(2) IR11(1) IR11(0) Current									
D5	IR11(5)	0	0	0	0	0	0	0	0	0			
D4	IR11(4)	0	0	0	0	0	0	0	1	0.2mA			
D3	IR11(3)	0		•				•		0.2mA step			
D2	IR11(2)	0	1	1	1	1	1	1	0	25.2mA			
D1	IR11(1)	0	1	1 1 1 1 1 1 1 25.4m/									
D0	IR11(0)	0	At RGB	At RGBISETpin 120kΩ connection									

Address 04h <R1 current2 setup >

Addres	35 0+11 1(1	All Kriculteniz setup >											
BIT	Name	Init				Fun	ction						
DII	Name	ITIIL		0			1						
D7	ı	-		-					-				
D6	IR12(6)	0	ID40(0)	12(6) IP12(5) IP12(4) IP12(3) IP12(2) IP12(1) IP12(0) Current									
		_	IR12(6)	IR12(5)	IR12(4)	IR12(3)	IR12(2)	IR12(1)	IR12(0)	Current			
D5	IR12(5)	0	0	0	0	0	0	0	0	0			
D4	IR12(4)	0	0	0	0	0	0	0	1	0.2mA			
D3	ID42/2)	0	•	-		-		•	-	0.2mA			
DS	IR12(3)	0						•		step			
D2	IR12(2)	0	1	1	1	1	1	1	0	25.2m			
D1	IR12(1)	0	1	1 1 1 1 1 1 1 25.4mA									
D0	IR12(0)	0	At RGBI	At RGBISETpin 120kΩ connection									

Address 05h <R1 Wave Pattern >

		vave Falletti >								
Namo	Init			Fund	ction					
INAITIC	11111		0			1				
-	-		-			-				
-	-		-			-				
-	-		-		-					
-	-		-			-				
PR1(3)	0	PR1(3) 0	PR1(2) 0			PR1(0) 0	Wave Pattern1			
PR1(2)	1	0	0	1)	1 0	Pattern2 Pattern3			
PR1(1)	1	1	• • 1	-		- - 1	Pattern14			
PR1(0)	1	1	1	1		0 1	Pattern15 Pattern16			
	- - - PR1(3) PR1(2)			PR1(3) 0 PR1(2) 1 PR1(1) 1 PR1(1) 1 PR1(1) 1 PR1(1) 1	Name Init - - - - - <t< td=""><td>PR1(3) 0 PR1(3) 0 PR1(2) 1 PR1(1) 1</td><td>Name Init 0 1 - - - - - -<!--</td--></td></t<>	PR1(3) 0 PR1(3) 0 PR1(2) 1 PR1(1) 1	Name Init 0 1 - - - - - - </td			

● Register Map - continued

Address 06h <G1 current1 setup >

/ tual co	33 0011 10		it i octup	otap ·									
BIT	Name	Init				Fun	ction						
DII	Name	IIII		0			1						
D7	1	-		-					-				
D6	IG11(6)	0	IG11(6)	11(6) IG11(5) IG11(4) IG11(3) IG11(2) IG11(1) IG11(0) Current									
D5	IG11(5)	0	0	0	0	0	0	0	0				
D4	IG11(4)	0	0	0	0	0	0	0	1	0.2mA			
D3	IG11(3)	0	-	•	•	•	•	•	•	0.2mA			
			•	•	•	•	•	•	•	step			
D2	IG11(2)	0	1	1	1	1	1	1	0	25.2mA			
D1	IG11(1)	0	1	1 1 1 1 1 1 1 25.4m									
D0	IG11(0)	0	At RGB	At RGBISETpin 120kΩ connection									

Address 07h <G1 current2 setup >

			'	Function									
BIT	Name	Init				Full	CUOII						
J	110.110			0			1						
D7	ı	-		-					-				
D6	IG12(6)	0	IG12(6)	12(6) IG12(5) IG12(4) IG12(3) IG12(2) IG12(1) IG12(0) Current									
D5	IG12(5)	0	0	0	0	0	0	0	0	0			
D4	IG12(4)	0	0	0	0	0	0	0	1	0.2mA			
D3	IG12(3)	0	•	•	•	•	•	•	•	0.2mA			
		-	•	•			•	•	-	step			
D2	IG12(2)	0	1	1	1	1	1	1	0	25.2mA			
D1	IG12(1)	0	1	1 1 1 1 1 1 25.4									
D0	IG12(0)	0	At RGB	At RGBISETpin 120kΩ connection									

Address 08h <G1 Wave Pattern >

Addies	55 0011 \G1	vvave	ave Fattern >									
BIT	Name	Init			Function	on						
DII	INAITIC	11110		0			1					
D7	-	-		-			-					
D6	-	-		-			-					
D5	-	-		-		-						
D4	Ī	-		-			-					
D3	PG1(3)	0	PG1(3)	PG1(2)	PG1(1) PG1(0)	Wave					
			0	0	0	0	Pattern 1					
D0	DO4(0)		0	0	0	1	Pattern 2					
D2	PG1(2)	1	0	0	1	0	Pattern 3					
			•	•	•	•	•					
D1	PG1(1)	1	•	•	-	•	•					
	(.)		1	1	0	1	Pattern 14					
			1	1	1	0	Pattern 15					
D0	PG1(0)	1	1	1	1	1	Pattern 16					
1		1										

Address 09h <B1 current1setup >

Addie	וםי וופט פפ	000.	it 13ctup >										
BIT	Name	Init				Fund	ction						
ы	INAITIE	11111		0			1						
D7	-	-		-					-				
D6	IB11(6)	0	IB11(6)	B11(6) IB11(5) IB11(4) IB11(3) IB11(2) IB11(1) IB11(0) Current									
D5	IB11(5)	0	0	0	0	0	0	0	0	0			
D4	IB11(4)	0	0	0	0	0	0	0	1	0.2mA			
D3	IB11(3)	0	•	•	•	•	•	•	•	0.2mA			
		_	•	•	•	•	•	•	•	step			
D2	IB11(2)	0	1	1	1	1	1	1	0	25.2mA			
D1	IB11(1)	0	1	1 1 1 1 1 1 1 25.4n									
D0	IB11(0)	0	At RGB	SETpin 120kΩ	2 connection								

Address 0Ah <B1 current2setup >

BIT	Name	Init				Fund	ction					
ы	Name	IIIIL		0			1					
D7	-	-										
D6	IB12(6)	0	IB12(6)	12(6) IB12(5) IB12(4) IB12(3) IB12(2) IB12(1) IB12(0) Curr								
D5	IB12(5)	0	0	0	0	0	0	0	0	0		
D4	IB12(4)	0	0	0	0	0	0	0	1	0.2mA		
D3	IB12(3)	0								0.2mA step		
D2	IB12(2)	0	1	1	1	1	1	1	0	25.2mA		
D1	IB12(1)	0	1	1 1 1 1 1 1 2								
D0	IB12(0)	0	At RGBI	At RGBISETpin 120kΩ connection								

Address OBh <B1 Wave Pattern >

Addres	ss ubn 	KB1 Wave Pattern >									
BIT	Name	Init			Fund	ction					
ы	INAITIC	11111		0			1				
D7	-	-		-			-				
D6	-	-		-			-				
D5	-	-		-							
D4	-	-		-			-				
D3	PB1(3)	0	PB1(3)	PB1(2)	PB1		PB1(0)	Wave Pattern1			
DO	DD4(2)	4	0	0	0		1	Pattern2			
D2	PB1(2)	1	0	0	1		0	Pattern3			
D1	PB1(1)	1	:								
	1 51(1)	'	1	1	0)	1	Pattern14			
			1	1 1 1 0		0	Pattern15				
D0	PB1(0)	1	1	1	1		1	Pattern16			

Address 0Ch <RGB2 time >

			10 7		ction				
BIT	Name	Init	0					1	
			SFRGB2(1)		SFRG	B2(0)	Slo	pe Down transition	
D7	SFRGB2(1)	0	0		()	0		
			0		1	l	Wave form cycle / 16		
			1		()	Wa	ave form cycle / 8	
DC	CEDCD3(0)	0	1		1	1	Wa	ave form cycle / 4	
D6	SFRGB2(0)	0		-	n logic control, and the reaction time of the ar rom a slope start to a slope end.			on is not included.	
			SRRGB2(1)		SRRGB2(0)			ope up transition	
D5	SRRGB2(1)	0	0		()		0	
			0		1			ive form cycle / 16	
			1		()		ave form cycle / 8	
D4	SRRGB2(0)	0	1		1			ave form cycle / 4	
D 4	SKKGB2(U)	U	It is a theoretical value "Slope time" is the time				log section	on is not included.	
D3	-	-	-					-	
			TRGB2(2)	TF	RGB2(1)	TRGB2(0))	Wave form cycle	
D2	TRGB2(2)	0	0		0	0		0.131 s	
			0		0	1		0.52 s	
			0	1		0		1.05 s	
D1	TRGB2(1)	0	0		1	1		2.10 s	
			1		0	0		4.19 s	
			1		0	1		8.39 s	
D0	TRGB2(0)	0	1		1	0		12.6 s	
			1		1	1		16.8 s	

Setting time is counted based on the frequency of OSC. The above-mentioned value is a value at the time of Typ (1MHz).

When operating by the external clock, input frequency is a value at the time of Typ (31.25kHz)

Refer to "ORGB Waveform Setting " for the detailed function of each register of this page.

Address 0Dh <R2 current 1setup>

/ tadi co	33 0011 112		Tit 130tup			Fund	ction					
BIT	Name	Init		0		T GIV	50011		1			
D7	-	-		-					-			
D6	IR21(6)	0	IR21(6)	221(6) IR21(5) IR21(4) IR21(3) IR21(2) IR21(1) IR21(0) Current								
D5	IR21(5)	0	0	0	0	0	0	0	0	0		
D4	IR21(4)	0	0	0	0	0	0	0	1	0.2mA		
D3	IR21(3)	0	-	•	•	•	•	•	•	0.2mA		
D2		0	•	•	•	•	•	•	•	step		
DZ	IR21(2)	U	1	1	1	1	1	1	0	25.2mA		
D1	IR21(1)	0	1	1 1 1 1 1 1 1 25.4m								
D0	IR21(0)	0	At RGB	At RGBISETpin 120kΩ connection								

Address 0Eh <R2 current 2setup>

BIT	Name	Init	•			Fund	ction						
ы	INAITIE	11111		0					1				
D7	-	-		-					-				
D6	IR22(6)	0	IR22(6)	22(6) IR22(5) IR22(4) IR22(3) IR22(2) IR22(1) IR22(0) Current									
D5	IR22(5)	0	0	0	0	0	0	0	0	0			
D4	IR22(4)	0	0	0	0	0	0	0	1	0.2mA			
D3	IR22(3)	0	:				•		•	0.2mA step			
D2	IR22(2)	0	1	1	1	1	1	1	0	25.2mA			
D1	IR22(1)	0	1	1 1 1 1 1 1 25.4									
D0	IR22(0)	0	At RGBI	At RGBISETpin 120kΩ connection									

Address 0Fh <R2 Wave Pattern setup>

Addres	55 0111 112	- vvavc	Pattern setup>						
BIT	Name	Init		Function					
DII	INAITIC	11111		0		1			
D7	-	-		-		-			
D6	-	-		-		-			
D5	-	-		-		-			
D4	-	-		-		-			
D3	PR2(3)	0	PR2(3)	PR2(2)	PR2(1)	PR2(0)	Wave		
D3	FR2(3)	U	0	0	0	0	Pattern 1		
			0	0	0	1	Pattern 2		
D2	PR2(2)	1	0	0	1	0	Pattern 3		
			•	•	•	•	•		
			•	•	•	•	•		
D1	PR2(1)	1	•	•	•	•	•		
			1	1	0	1	Pattern 14		
D0	DD2(0)		1	1	1	0	Pattern 15		
D0	PR2(0)	1	1	1	1	1	Pattern 16		

● Register Map - continued

Address 10h <G2 current 1setup>

Addie	33 1011 102		it isclup-									
BIT	Name	Init		Function								
ы	INAITIE	11111		0				1				
D7	-	-		-			-					
D6	IG21(6)	0	IG21(6)	IG21(5)	IG21(4)	IG21(3)	IG21(2)	IG21(1)	IG21(0)	Current		
D.F.	1004(5)	^	1621(0)	1621(3)	1621(4)	1621(3)	1621(2)	1621(1)	1621(0)	Current		
D5	IG21(5)	0	0	0	0	0	0	0	0	0		
D4	IG21(4)	0	0	0	0	0	0	0	1	0.2mA		
D3	IG21(3)	0	•	•		•		•		0.2mA		
DS	1021(3)	U								step		
D2	IG21(2)	0	1	1	1	1	1	1	0	25.2mA		
D1	IG21(1)	0	1	1	1	1	1	1	1	25.4mA		
D0	IG21(0)	0	At RGB	ISETpin 120kΩ	2 connection							

Address 11h <G2 current 2setup>

/ taarct	33 1111 102		it 230tap									
BIT	Name	Init		Function								
DII	INAITIE	11111		0				1				
D7	ı	-		-			-					
D6	IG22(6)	0	IG22(6)	IG22(5)	IG22(4)	IG22(3)	IG22(2)	IG22(1)	IG22(0)	Current		
D5	IG22(5)	0	0	0	0 `	0	0)	0	0)	0		
D4	IG22(4)	0	0	0	0	0	0	0	1	0.2mA		
D3	IG22(3)	0	•	•	•	•	•	•	•	0.2mA		
		_	•	•	•	•	•	•	•	step		
D2	IG22(2)	0	1	1	1	1	1	1	0	25.2mA		
D1	IG22(1)	0	1	1	1	1	1	1	1	25.4mA		
D0	IG22(0)	0	At RGBI	ISETpin 120kΩ	2 connection							

Address 12h <G2 Wave Pattern setup >

Addres	55 1211 \G2	vvave	Pattern setup >						
DIT	Name	lm:4		Function					
BIT	Name	Init		0		1			
D7	-	-		-		-			
D6	-	-		-		-			
D5	-	-		-		-			
D4	-	-		-		-			
D3	PG2(3)	0	PG2(3)	PG2(2)	PG2(1)	PG2(0)	Wave		
	(-)		0	0	0	0	Pattern 1		
			0	0	0	1	Pattern 2		
D2	PG2(2)	1	0	0	1	0	Pattern 3		
			•	•		•	•		
D1	PG2(1)	1	•	•	•	•	•		
٥.	1 02(1)		1	1	0	1	Pattern 14		
			1	1	1	0	Pattern 15		
D0	PG2(0)	1	1	1	1	1	Pattern 16		

● Register Map - continued

Address 13h <B2 current 1setup>

Addies	בטי ווטו סב	· oarror	it isclup-								
BIT	Name	Init		Function							
DII	INAITIE	IIIIC		0				1			
D7	-	-		-					-		
D6	IB21(6)	0	IB21(6)	IB21(5)	IB21(4)	IB21(3)	IB21(2)	IB21(1)	IB21(0)	Current	
D5	IB21(5)	0	, ,	1021(3)	. ,	1021(3)	_ ` ′	_ ` ′	_ ` ,	_	
DO	1021(0)	U	0	U	0	U	0	0	0	0	
D4	IB21(4)	0	0	0	0	0	0	0	1	0.2mA	
D3	IB21(3)	0	•	•	•	•	•	•	•	0.2mA	
	1021(0)	Ŭ		-	•			•	•	step	
D2	IB21(2)	0	1	1	1	1	1	1	0	25.2mA	
D1	IB21(1)	0	1	1	1	1	1	1	1	25.4mA	
D0	IB21(0)	0	At RGB	ISETpin 120k0	2 connection	·	·	·	·		

Address 14h <B2 current 2setup>

BIT	Name	Init	•	Function							
ы	INAITIE	11111		0				1			
D7	-	-		-					-		
D6	IB22(6)	0	IB22(6)	IB22(5)	IB22(4)	IB22(3)	IB22(2)	IB22(1)	IB22(0)	Current	
D5	IB22(5)	0	0	0	0	0	0	0	0	0	
D4	IB22(4)	0	0	0	0	0	0	0	1	0.2mA	
D3	IB22(3)	0								0.2mA step	
D2	IB22(2)	0	1	1	1	1	1	1	0	25.2mA	
D1	IB22(1)	0	1	1	1	1	1	1	1	25.4mA	
D0	IB22(0)	0	At RGBI	SETpin 120kΩ	2 connection						

Address 15h <B2 Wave Pattern setup >

Addies	5 1311 702	vvave	rattern setup /					
BIT	Name	Init			Function	on		
DII	Name	11110	0			1		
D7	-	-		-		-		
D6	-	-		-		-		
D5	-	-		-		-		
D4	-	-		-		-		
D3	PB2(3)	0	PB2(3)	PB2(2)	PB2(1) PB2(0)	Wave	
	. ,		0	0	0	0	Pattern 1	
D0	DD0(0)	4	0	0	0	1	Pattern 2	
D2	PB2(2)	1	0	0	1	0	Pattern 3	
			•	•	•	•	•	
D1	PB2(1)	1	•	•	•	•	•	
	(.)	-	1	1	0	1	Pattern 14	
			1	1	1	0	Pattern 15	
D0	PB2(0)	1	1	1	1	1	Pattern 16	
1								

Address 40h < DC/DC driver function >

Addres	55 40II \ DI		invertunction >				
BIT	Name	Init			Fund	ction	
DII	Name	HIIL		0			1
D.7	VOLIT(4)	_	VOUT(1)	VOUT(0)	DC/DC	output voltage	
D7	VOUT(1)	0	0	0		3.9V	
			0	1		4.2V	
D6	VOUT(0)	0	1	0		4.5V	
В	VOO1(0)	U	1	1		4.8V	
D.F.	DODOMB		DCDCMD	DCDCFON	DC/DC	Return mode	DC/DC ON/OFF control
D5	DCDCMD	0	0	0	LED	pin Return	LED ON
			0	1	LED	pin Return	LED ON
D4	DCDCFON	0	1	0	Output v	oltage fixation	LED ON
D4	DODOFON	U	1	1	Output v	oltage fixation	Forced ON
D3	-	-		-			-
D2	-	-		-			-
D1	-	-		-			-
D0	-	-		-		-	

Address 41h <LED pin function setup>

ddre	ss 41h <le< th=""><th>יו וווק ט</th><th>unction setup></th><th></th><th></th><th></th><th></th><th></th></le<>	יו וווק ט	unction setup>						
BIT	Name	Init			Fund	ction			
ы	Name	11111		0		1			
D7	-	-		-			-		
D6	-	-		-			-		
D5	-	-		-			-		
D4	-	-		-			-		
Б0	DODODW(4)	•	RGB2PW(1)	RGB2PW(0)	R2 con	nection	G2 connection	B2 connection	
D3	RGB2PW(1)	0	0	0	VB	AT	VBAT	VBAT	
			0	1	VB	AT	VBAT	VOUT	
DO	DCD2DW(0)	0	1	0	VB	AT	VOUT	VOUT	
D2	RGB2PW(0)	0	1	1	VO	UT	VOUT	VOUT	
			RGB1PW(1)	RGB1PW(0)	R1 con	nection	G1 connection	B1 connection	
D1	RGB1PW(1)	0	0	0	VB		VBAT	VBAT	
			0	1	VB	AT	VBAT	VOUT	
DO	DCD4DW(0)	_	1	0	VB	AT	VOUT	VOUT	
D0	RGB1PW(0)	0	1	1	VO	UT	VOUT	VOUT	

RGB*PW (1:0) does not assume to change dynamically. Please perform a fixed setup per design.

And, do the setup of RGB*PW (1:0) when each LED is Off.

● RGB LED Driver Operation Description

- Two drivers "RGB1 (R1LED, G1LED, B1LED)" and "RGB2 (R2LED, G2LED, B2LED)" are mounted.
- A slope function is incorporated to control drivers independently.
- Refer to ●RGB Waveform Setting for more information about output waveform setting.
- The LED current can be set via a resistance value (RISET) to be connected to the RGBISET terminal. The maximum current value can be derived from the following expression:

ILEDmax [A] = $3.048 / RISET [k\Omega] (Typ)$

However, this setting must be made so that the maximum current value can be less than or equal to 30.48mA. In addition, the RGBISET terminal has an over current protection circuit to prevent the excessive LED current from flowing for low impedance to the ground.

• Connection of each LED of RGB can be set up in VBAT or VOUT by the register RGB1PW (1:0) and RGB2PW (1:0). When Vf is low, it is connected to VBAT, and it is possible that efficiency is raised. When a VBAT connection is chosen, a return route to the DC/DC circuit is interrupted, and it works as a simple constant current driver. In this case, set it up to be less low than the saturation voltage (0.2V) of the fixed electric current circuit.

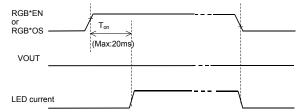


Figure 8. LED electric current When DC/DC isn't used.

●The synchronism of RGB1/RGB2

The period of RGB1 and RGB2 and start, stop timing can be set up independently.

When synchronizes RGB1 and RGB2, You must start an internal counter at the same time under the state of resetting. (Internal Counter is prepared for each of RGB1 and RGB2, so you must reset both.)

<How to reset internal Counter>

Inside Counter can be reset by carrying out one of following actions.

- Reset by hard reset (RSTB_IL). (RGB1, RGB2 is reset together.)
- Reset by soft reset. (RGB1, RGB2 is reset together.)
- It is written register of the current setup (I1 I2), the slope setup, the period setup and the pattern setup. Internal Counter of RGB1 is reset when it is written between Address=0Bh from 02h. Internal Counter of RGB2 is reset when it is written between Address=15h from 0Ch. Counter is reset as to overwriting the same value.

Note)

Internal Counter isn't reset if write RGB1EN =L and RGB2EN =L. (Address=01h). When it write RGB1EN=L (RGB2EN=L), inside Counter is held, and IC will operate from the held state at next restart.

RGB Waveform Setting

Various kinds of RGB control can be implemented by designating waveform cycles, waveform patterns, current settings 1, 2 and rising/falling slope times.

To activate a RGB waveform, a continuous operation via RGB*EN or a single-shot operation via RGB*OS can be selected. In addition, when control via the external terminal RGB*CNT is enabled via RGB*MEL, the corresponding LED can be lit in synchronization with the external signal.

1. Waveform cycle

- A single cycle time is set for a waveform pattern.
- This setting can be made independently for RGB1 and RGB2.

2. Waveform pattern

- · A pattern in a waveform cycle is set.
- Sixteen types of waveform patterns can be set in units of waveform patterns.
- For concrete waveform patterns, refer to the timing diagram shown on the next page.

3. Current settings 1 and 2 (I1, I2)

- Two currents (I1, I2) in a waveform pattern are set.
- When the maximum current value is 25.4mA, it is possible to set the current ranging from 0 to 25.4mA with an increment of 0.2mA (128 steps).
- The polarity of a waveform is determined by the greater-than/ less-than relationship in the current setting.
- This setting can be made in units of terminals.

4. Rising/falling slope time

- A current change time during switching between current settings 1 and 2 is set.
- A time per step (0.2mA) is calculated based on a difference between the currents selected in current settings 1, 2 and a setting slope time.
- For this reason, a time per step (0.2mA) is short when a difference between setting currents I1 and I2 is large. In contrast, it is long when a difference between setting currents I1 and I2 is small.
- Regardless of current settings 1 and 2, a rising slope time applies at current increase and a falling slope time applies at current decrease. For concrete waveform images, refer to the timing diagram shown on the next page.

5. External terminal synchronization control

When control via the external terminal RGB*CNT is enabled via RGB*MEL, lighting is enabled if the input external signal goes "H." In contrast, it is disabled if the external input signal goes "L." In this way, synchronization with the external signal is enabled so that LED can be blinked in conjunction with a ringing tone (a melody signaling a ring tone).

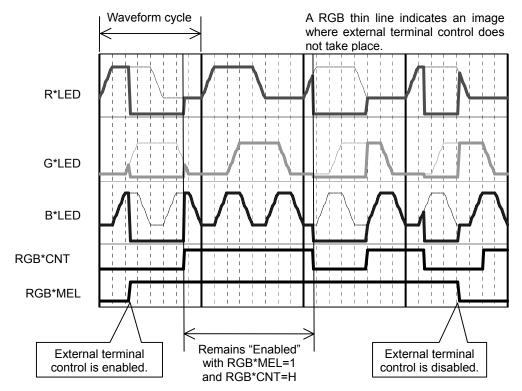


Figure 9.Example of RGB*CNT

● RGB Waveform Setting - continued

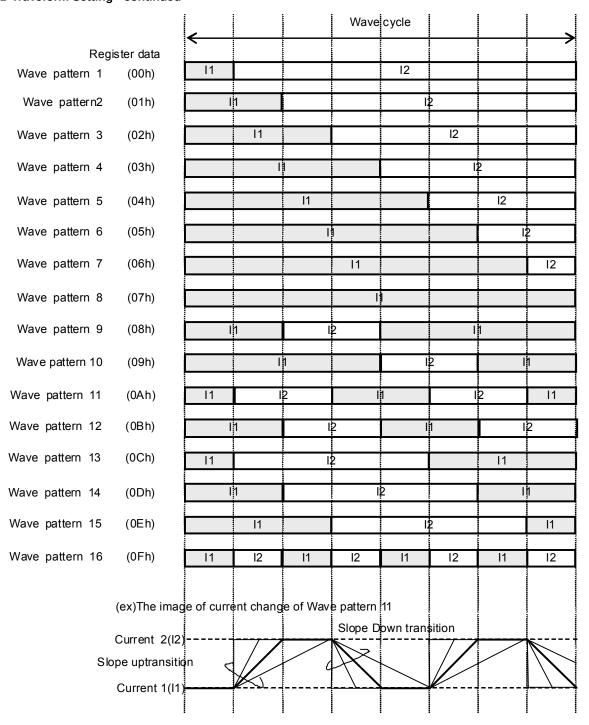


Figure 10. RGB wave setting timing diagram

● RGB Waveform Setting - continued

6. Clock I/O

A reference clock I/O function is mounted in this IC chip. When two IC chips are used to extend an illumination capability, clock supply to the other RGB LED driver can be accomplished for synchronization with this LSI chip. This setting can be made via the register.

Clock output can be made with CLKEN=1 and CLKMD=1.

Please refer to the table in Sleep operation mode for details.

7. Sleep operation mode

It can be set as a sleep mode by SLPMD=1 setup. In a sleep mode, all the LED current under lighting operation serves as low consumption operation mode at 0mA. Therefore, an analog block unnecessary for operation can be turned off. In an internal clock sleep mode, a block required for clock generation remains turning on.

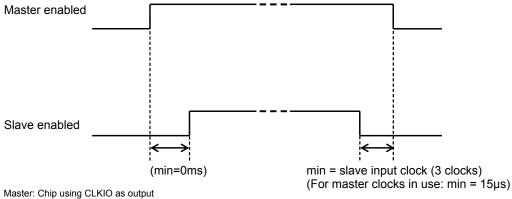
Starting sequence of charge pump enters by LED lighting. Therefore, lighting timing changes compared with the normal mode.

CLKEN	CLKMD	FSEL	SLPMD	CLKIO Terminal condition	Illuminations Sleep mode
0	*	*	*	Clock I/O invalid	Normal mode
	0	1	0	Input (fin=31.25kHz)	Normal mode
	U	ı	1	Input (fin=31.25kHz)	External clock Sleep mode
1		0	0	Output (fout=250kHz)	Normal mode
	1	1	0	Output (fout=31.25kHz)	Normal mode
		ı	1	Output (fout=31.25kHz)	Internal clock Sleep mode

Setup other than the above is prohibition.

●When two BD2812GU drivers are used and the clock is shared by CLKIO:

Because a sequence is already programmed within an IC chip for RGB falling, "Enable" shall be set to "OFF" and clock supply shall be continued for at least three clocks so that operations can be performed using external clocks

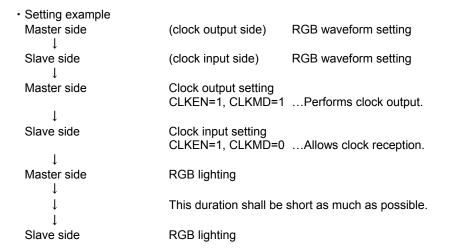


Slave: Chip using CLKIO as output

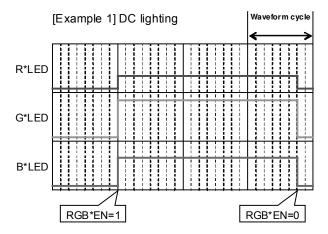
Figure 11. The example of a setting at used two ICs

* Even in independent slave mode, its setting "Enable" shall be reset to "OFF" and then clock supply must be continued or 3 clocks or more.

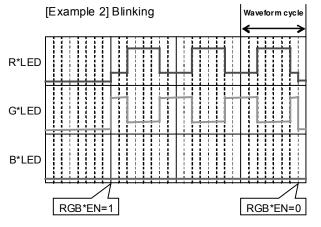
Clock I/O switching shall be avoided during RGB operation. Enable: CLKEN, RGB1EN, RGB2EN, RGB1OS, RGB2OS



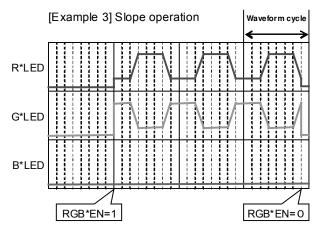
8. RGB waveform setting examples



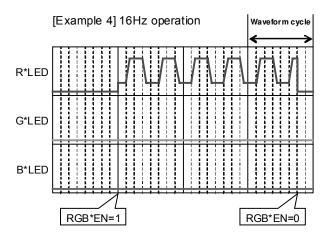
Selecting a waveform pattern 8 causes a continuous normal operation to take place through the setting current 1.



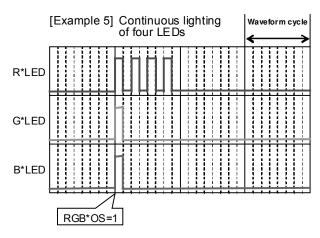
Setting a rising/falling slope time to "0" causes blinking to take place. Phase switching takes place via the setting currents of R and G.



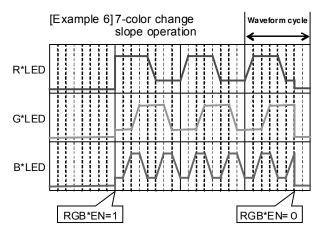
When a rising/falling slope time is longer than the setting made in example 2, a continuous color change is made by slope operation.



Combining the settings of a waveform pattern 11 and a waveform cycle 131ms causes blinking at a rate of 15.3Hz (approx. 16Hz).



This example shows that lighting occurs continuously in the order of white, red, red and red. To achieve this, waveform patterns 16, 1 and RGB*OS single cycle operation need to be combined.



R, G and B waveform patterns are set in a way that any of R, G and B changes constantly.

9. RGB slope waveforms

Example of waveform at activation (Waveform pattern=14)
 Current setting: I1 < I2

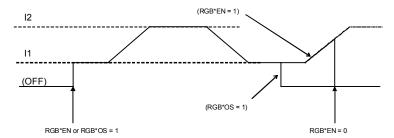


Figure 12. The example 1 of a wave pattern at LED current start-up

Current setting: I1 > I2

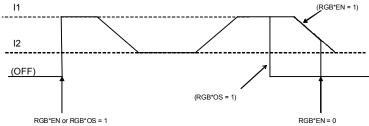


Figure 13. The example 2 of a wave pattern at LED current start-up

· Current difference in each channel (example)

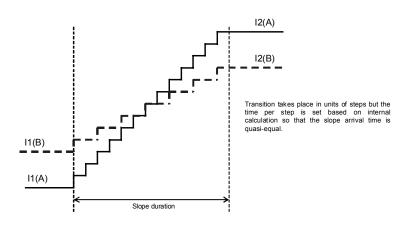


Figure 14. The slope waveform by the difference in an LED current

9. Setting change in slope duration

A slope operation is performed by an internal sequencer.

When an attempt is made to change the setting (Address 02h to 15h) in a slope duration, the active slope operation is reset and a newly set slope operation is restarted.

In this case, however, LED lighting stops for a maximum of 16.4ms (OSC frequency=Typ) for synchronization with the internal clock until the operation is restarted.

Description of REG Operations

Activation

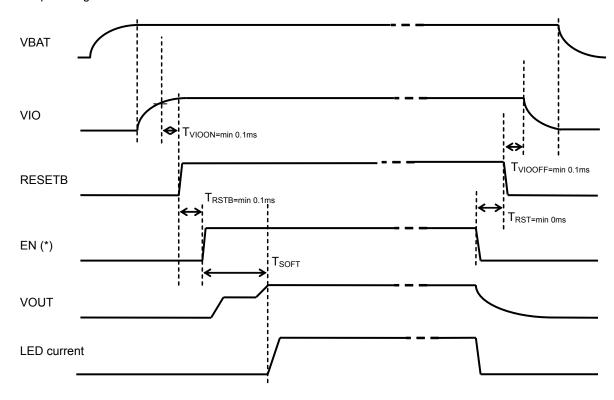
The DC/DC circuit is activated when any LED is subject to lighting control (DCDCFON=0).

(However, this is true only when the output (VOUT) of the DC/DC circuit is set as a LED connection destination.)

A soft start function is available to prevent the rush current at DC/DC circuit activation.

Note that voltage should apply to both VBAT and VIO as follows:

DCDCMD=1 must be set in the fixed voltage mode and DCDCMD=DCDCFON=1 must be set when DCDC output takes place regardless of LEDs.



 $(\mbox{\ensuremath{^{*}}})$ An EN signal means the following in the upper figure.

EN = "MLEDEN" or "W*EN" or "RGB*EN" or "RGB*OS" (= LED The LED lighting control of a setup of connection VOUT)

But, as for Ta > T_{TSD} (Typ: 195° C), a protection function functions, and an EN signal doesn't become effective.

Tsoft changes by the capacitor connected to VOUT and inside OSC.

 T_{SOFT} is Typ 200µs (when the output capacitor of VOUT =1.0µF).

Figure 15. DC/DC starting sequence

Over voltage protection/Over current protection

The DC/DC circuit output (VOUT) is provided with an over voltage protection function and an over current protection function. VOUT over voltage detection voltage: approx. 6.0V (during a VOUT voltage rise)

A detection voltage has a hysteresis and its detection cancel voltage is approx. 5.75V (reference design value). In addition, when the VOUT output is short-circuited to GND, the leak current is suppressed via the over current protection function.

Description of REG Operations - continued

Mode transition

A step-up (pressure rising) multiple switches automatically depending on the VBAT voltage and VOUT terminal voltage.

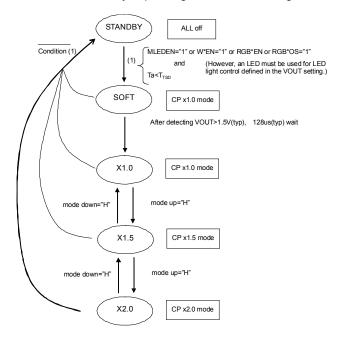


Figure 16. DC/DC state transition diagram

The charge pump mode transits as follows.

<Mode transition: $x1.0 \rightarrow x1.5 \rightarrow x2.0$ >

VBAT and VOUT are compared and mode transition is allowed only when the following conditions are satisfied.

```
Mode transition from x1.0 to x1.5

VBAT ≤ VOUT + (Ron10×lout)

(LED terminal feedback: VOUT = Vf+0.2(Typ))

Mode transition from x1.5 to x2.0

VBAT×1.5 ≤ VOUT + (Ron15×lout)

(LED terminal feedback: VOUT = Vf+0.2(Typ))
```

Where, Ron10 and Ron15 represent a 0n resistance at a charge pump. Ron10=1 Ω (Typ), Ron15=5 Ω (Typ) (design value)

<Mode transition: $x2.0 \rightarrow x1.5 \rightarrow x1.0$ >

1. VOUT and VBAT rates are detected and mode transition is performed only when a prescribed rate is exceeded. The rates are as follows:

```
Mode transition from x1.5 to x1.0

VBAT/VOUT=1.07 (design value)

Mode transition from x2.0 to x1.5

VBAT/VOUT=0.96 (design value)
```

2. If DCDCMD (register00h) '1'→'0' (switch from output voltage fixed mode to LED pin return mode) is operated, a mode down will be performed until it fulfils mode up conditions.

Description of Other Operations

1. Reset

There are two types of reset: software reset and hardware reset.

(1)Software reset

- Setting the register (SFTRST) to "1" causes all the registers to be initialized.
- The registers subject to software reset automatically return to zero (Auto Return 0).

(2)Hardware reset

- · Changing the RESETB terminal setting from "H" to "L" causes a state subject to hardware reset.
- Attempting hardware reset causes the states of all registers and output terminals to be initialized to their initial values, so that address reception is entirely stopped.
- · Attempting reset in the hardware reset state causes the RESETB terminal state to change from "L" to "H" and vice versa.
- The RESETB terminal is provided with a filter circuit and a duration of 5µs or less with the terminal set to "L" is not recognized as hardware reset.

(3) Reset sequence

• When hardware reset is attempted during software reset, software reset is already cleared when hardware reset is cleared (because the software reset initial value is 0).

2. Thermal shutdown

The thermal shutdown is effective for LED and OSC portions.

The thermal shutdown function is activated when the detected temperature is approx. 195°C.

The detected temperature has a hysteresis and the detection cancel temperature is approx 175°C(reference value in design).

3. I/O portion

While the RESETB terminal is in "L" state, no input signal is propagated to the IC logic portion because SDA and SCL input buffer operations are all stopped.

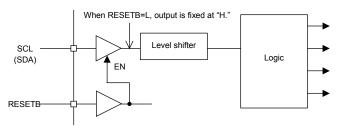


Figure 17. I/O block

Special care should be taken because a current path may be formed via a terminal protection diode, depending on an I/O power-on sequence or an input level.

4. Power on/off sequence

Voltage shall be applied as follows at driver activation. When a delay element is connected to a VIO voltage source and a reset cancel signal is input to the RESETB terminal, special care should be taken to the rising time of VIO voltage to delay the RESETB signal without fail.

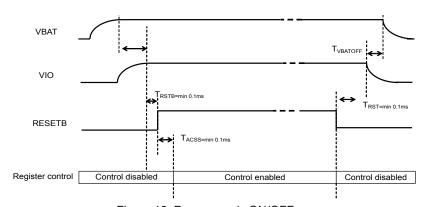


Figure 18. Power supply ON/OFF sequence

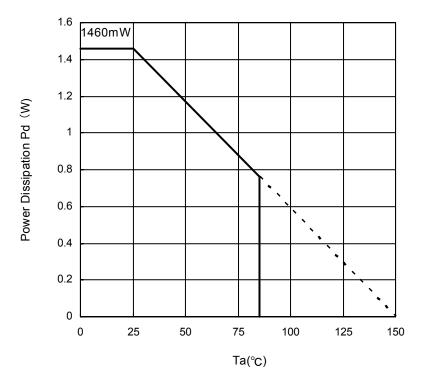
Description of Other Operations - continued

5. Terminating the unused terminals

Be sure to set the test terminals and unused terminals as summarized in the following table. In addition, refer to the preceding equivalent circuit and terminate the above terminals in a way that no problem occurs during actual use.

T1, T2, T3, T4	Short to GND because pin for test
LED terminals not to be used	Short-circuit these terminals to GND. In this case, don't set the registers related to LEDs not to be used.
RGB1CNT, RGB2CNT	Short-circuit these terminals to GND. (Built-in pull-down resistance)
CLKIO	Short-circuit these terminals to GND. (Built-in pull-down resistance)
ADDSEL	Be sure to short-circuit this terminal to VBAT or GND.

● Power Dissipation (On the ROHM's standard board)



Information of the ROHM's standard board Material: glass-epoxy Size: 50mm×58mm×1.75mm (8Layer)

Figure 19. Power Dissipation

Operational Notes

(1) Absolute Maximum Ratings

An excess in the absolute maximum ratings, such as supply voltage, temperature range of operating conditions, etc., can break down devices, thus making impossible to identify breaking mode such as a short circuit or an open circuit. If any special mode exceeding the absolute maximum ratings is assumed, consideration should be given to take physical safety measures including the use of fuses, etc.

(2) Power supply and ground line

Design PCB pattern to provide low impedance for the wiring between the power supply and the ground lines. Pay attention to the interference by common impedance of layout pattern when there are plural power supplies and ground lines. Especially, when there are ground pattern for small signal and ground pattern for large current included the external circuits, please separate each ground pattern. Furthermore, for all power supply pins to ICs, mount a capacitor between the power supply and the ground pin. At the same time, in order to use a capacitor, thoroughly check to be sure the characteristics of the capacitor to be used present no problem including the occurrence of capacity dropout at a low temperature, thus determining the constant.

(3) Ground voltage

Make setting of the potential of the ground pin so that it will be maintained at the minimum in any operating state. Furthermore, check to be sure no pins are at a potential lower than the ground voltage including an actual electric transient.

(4) Short circuit between pins and erroneous mounting

In order to mount ICs on a set PCB, pay thorough attention to the direction and offset of the ICs. Erroneous mounting can break down the ICs. Furthermore, if a short circuit occurs due to foreign matters entering between pins or between the pin and the power supply or the ground pin, the ICs can break down.

(5) Operation in strong electromagnetic field

Be noted that using ICs in the strong electromagnetic field can malfunction them.

(6) Input pins

In terms of the construction of IC, parasitic elements are inevitably formed in relation to potential. The operation of the parasitic element can cause interference with circuit operation, thus resulting in a malfunction and then break down of the input pin. Therefore, pay thorough attention not to handle the input pins, such as to apply to the input pins a voltage lower than the ground respectively, so that any parasitic element will operate. Furthermore, do not apply a voltage to the input pins when no power supply voltage is applied to the IC. In addition, even if the power supply voltage is applied, apply to the input pins a voltage lower than the power supply voltage or within the guaranteed value of electrical characteristics.

(7) External capacitor

In order to use a ceramic capacitor as the external capacitor, determine the constant with consideration given to a degradation in the nominal capacitance due to DC bias and changes in the capacitance due to temperature, etc.

(8) Thermal shutdown circuit (TSD)

This LSI builds in a thermal shutdown (TSD) circuit. When junction temperatures become detection temperature or higher, the thermal shutdown circuit operates and turns a switch OFF. The thermal shutdown circuit, which is aimed at isolating the LSI from thermal runaway as much as possible, is not aimed at the protection or guarantee of the LSI. Therefore, do not continuously use the LSI with this circuit operating or use the LSI assuming its operation.

(9) Thermal design

Perform thermal design in which there are adequate margins by taking into account the permissible dissipation (Pd) in actual states of use.

(10) About the pin for the test, the un-use pin

Prevent a problem from being in the pin for the test and the un-use pin under the state of actual use. Please refer to this Datasheet. And, as for the pin that doesn't specially have an explanation, ask our company person in charge.

(11) About the rush current

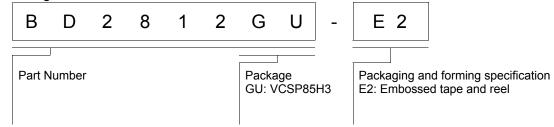
Because the rush current flows momentarily for internal logic instability caused by a power-on sequence or delay, special care should be taken to the power supply coupling capacity, power supply, ground pattern wiring width and wiring.

Status of this document

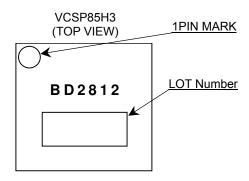
The Japanese version of this document is formal specification. A customer may use this translation version only for a reference to help reading the formal version.

If there are any differences in translation version of this document formal version takes priority.

Ordering Information

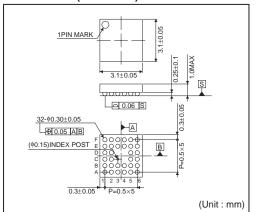


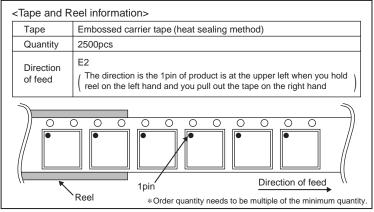
●Marking Diagram



Physical Dimension Tape and Reel Information

VCSP85H3 (BD2812GU)





Revision History

Date	Revision	Changes
26.Sep.2012	001	New Release

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CLASSIV		CLASSⅢ	

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 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
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 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
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- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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